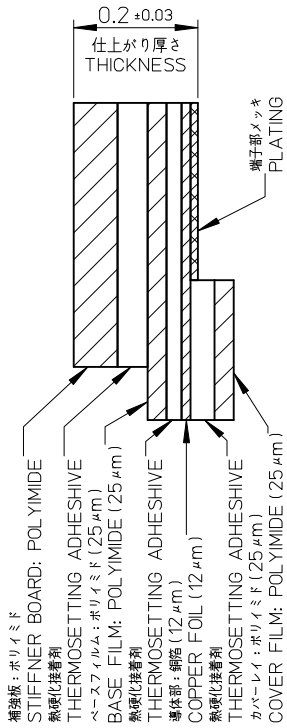


注記 NOTES

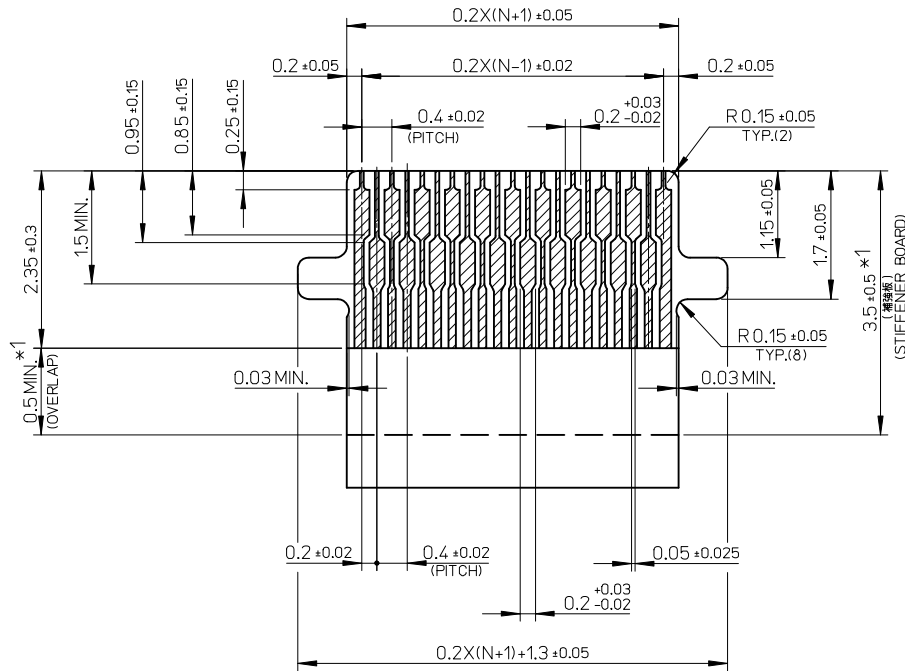
- 使用材料 MATERIALS  
 ハウジング : 液晶ポリマー(LCP) ガラス充填、UL94V-0、ナチュラル(白色系)  
 アクチュエータ: ポリアミド(PA) ガラス充填、UL94 HB、黒色  
 奇数端子 : 銅合金、ニッケル下地、金メッキ  
 偶数端子 : 銅合金、ニッケル下地、金メッキ  
 補強金具 : 銅合金、ニッケル下地、金メッキ  
 HOUSING : LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED UL94V-0, NATURAL(WHITE)  
 ACTUATOR : POLYAMIDE(PA), GLASS FILLED UL94 HB, BLACK  
 ODD TERMINAL : COPPER ALLOY, Gold OVER Nickel PLATING  
 EVEN TERMINAL : COPPER ALLOY, Gold OVER Nickel PLATING  
 FITTING NAIL : COPPER ALLOY, Gold OVER Nickel PLATING
- 端子、補強金具のコプラナリティーは 0.1以下とする  
 COPLANALITY OF SOLDER TAILS AND FITTING NAILS: 0.1MAX.
- 一般公差: ± 0.3  
 GENERAL TOLERANCES: ±0.3
- ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT

15.6	16.4	17.22	16.0	17.75	503419-0810	81
13.6	14.4	15.22	14.0	15.75	503419-0710	71
12.8	13.6	14.42	13.2	14.95	503419-0670	67
E	D	C	B	A	EMBOSSED PACKAGE	極数
CONNECTIR SERIES NO. 503419-***8						CIRCUITS
オーダー番号 ODEER NO.						

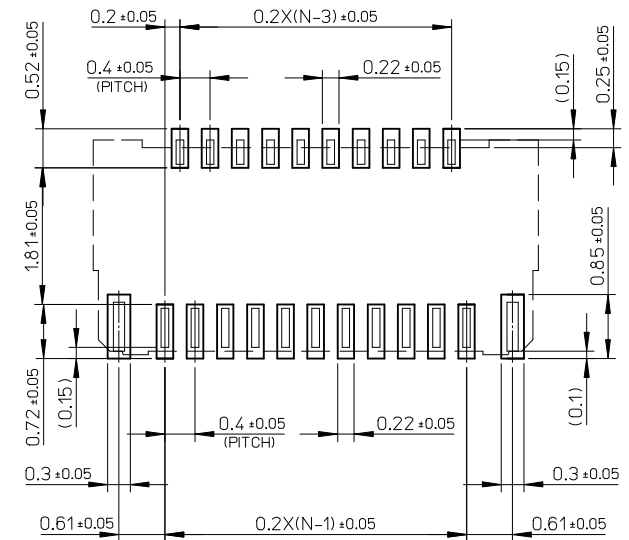
REVISED EC NO: J2015-0631 DRAWN: NKONDO 2014/11/11 CHKD: TAKAHASHI 2014/11/11 APPR: YNOGAWA 2014/11/11	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY NKONDO		DATE 2011/11/15		TITLE 0.2 FPC CONN E/O BTM CONTACT TYPE HGT=0.9MM			
		10 OVER 30 UNDER	± ---	CHECKED BY HIJIMA		DATE 2011/11/15					
		30 OVER	± ---	APPROVED BY KMORIKAWA		DATE 2011/11/16					
D	REV	ANGULAR ±1° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 503419-***8		DOCUMENT NO. SD-503419-001		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



FPC構成推奨仕様  
STRUCTURE OF FPC



適合するFPC推奨寸法 (参考)  
APPLICABLE FPC  
PATTERN DIMENSIONS(REF.)  
(端子部仕上がり厚さ: 0.2 ± 0.03)  
(THICKNESS: 0.2 ± 0.03)



参考基板レイアウト  
RECOMMENDED PCB  
PATTERN DIMENSIONS(REF.)

推奨ベスト厚 : 100μm  
推奨マスク開口率 : 80%  
RECOMMEND SCREEN THICKNESS : 100μm  
RECOMMEND SCREEN OPEN RATIO : 80%

・FPCについて (ABOUT FPC)

抜き方向は、導体側から補強板側を推奨します  
補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します  
なお、接着剤の接点部への付着は導通不良の原因となりますので  
染み出しがないよう、お願いします

RECOMMENDED PUNCHER DIRECTION:  
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE

RECOMMENDED MATERIAL:  
STIFFENER BOARD: POLYIMIDE  
BONDING AGENT: THERMOSETTING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON  
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT  
THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY

・FPCパターンメッキ仕様

金メッキ: 0.14μm 以上  
下地ニッケルメッキ: 2~6μm

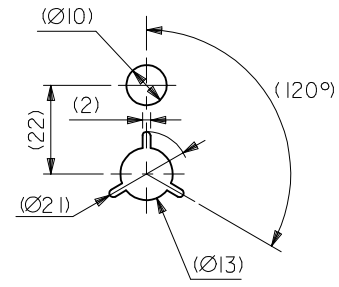
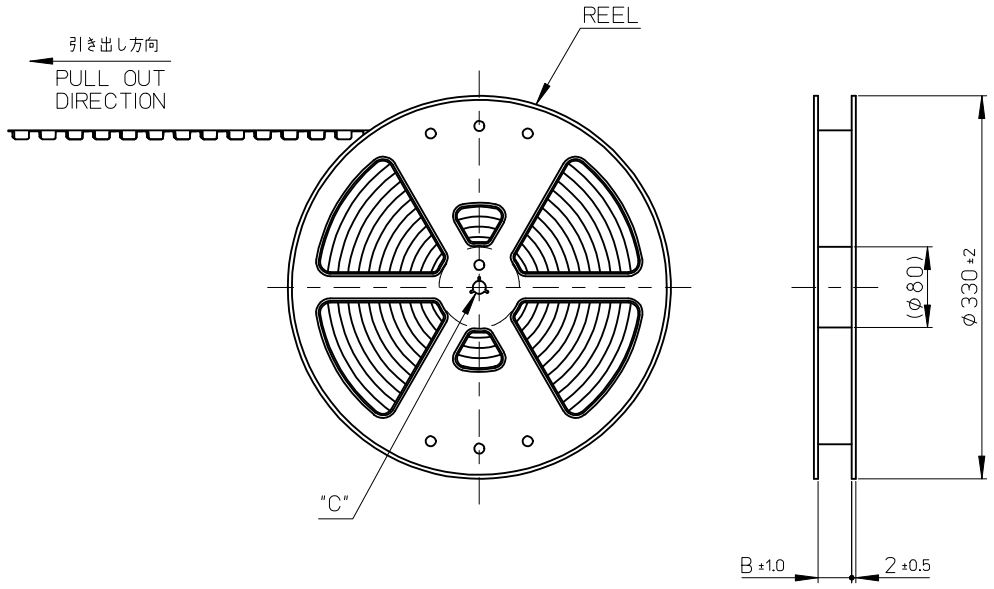
FPC PATTERN PLATING

GOLD PLATING : 0.14μm MINIMUM  
NICKEL UNDER PLATING : 2~6μm

\*1 補強板長さが図面通り確保できない場合は、カバーレイと  
補強板のオーバーラップ寸法を 0.5mm 以上としてください

WHEN STIFFENER BOARD DIMENSION CAN NOT  
SECURE AS DRAWING, PLEASE GIVE THE OVERLAP  
SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

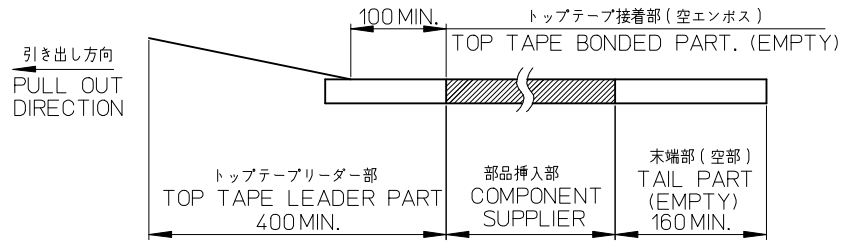
SEE SHEET 1 OF 2	EC NO: J2015-0631 DRAWN: DR/MNKONO 2014/11/11 CHKD: K/KAHASHI 2014/11/11 APPR: Y/NOGAWA 2014/11/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY NKONDO	DATE 2011/11/15	TITLE 0.2 FPC CONN E/O BTM CONTACT TYPE HGT=0.9MM			
		10 OVER 30 UNDER	± ---	CHECKED BY HIJIMA	DATE 2011/11/15				
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2011/11/16				
		ANGULAR	± 1 °	MATERIAL NO. 503419-***8	DOCUMENT NO. SD-503419-001	SHEET NO. 2 OF 2			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



DETAIL "C"

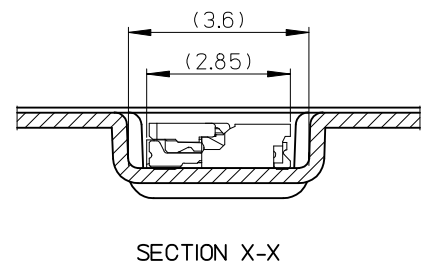
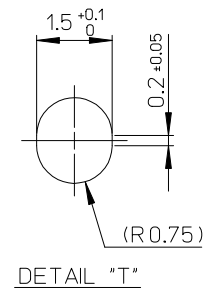
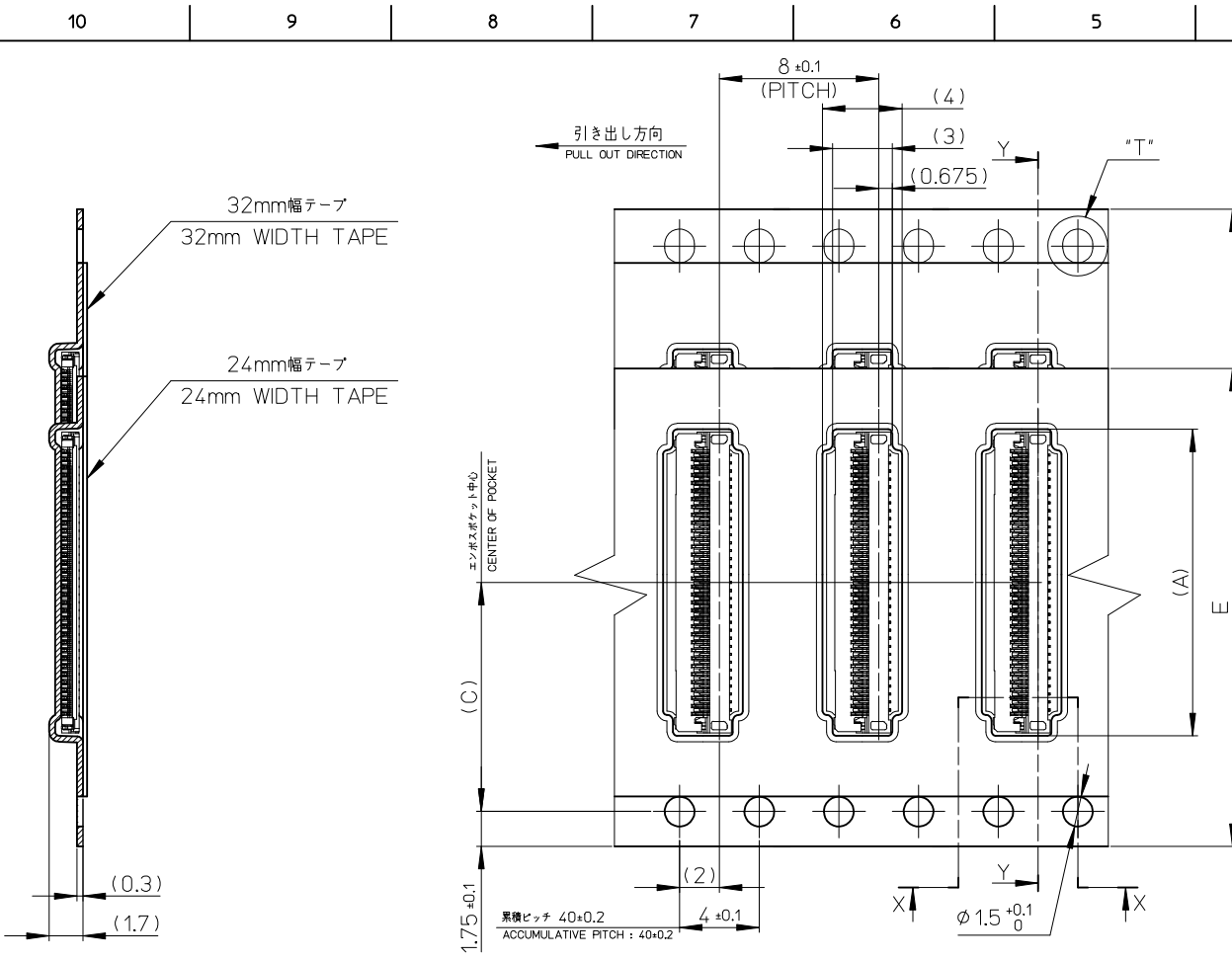
注記 NOTES

- 製品詳細寸法については図面 SD-503419-001を参照下さい。  
RE DETAILED DIMENSION. SEE SD-503419-001
- 梱包数量: 5000個/リール  
NUMBER OF CONNECTORS : 5000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- 材料 MATERIAL  
 キャリアテープ (CARRIER TAPE): ポリスチレン (POLYSTYRENE)  
 トップテープ (TOP TAPE): PET, PE, PEF  
 リール (REEL): ポリスチレン (PS) <リサイクル材を含む>  
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- トップテープの剥離強度については、IEC60286-3に準拠  
 TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

REVISED EC NO: J2015-0631 DRWN: NKONDO 2014/11/11 CHKD: TAKAHASHI 2014/11/11 APPR: YNOGAWA 2014/11/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY NKONDO	DATE 2011/11/15	TITLE 0.2 FPC CONN. E/O TAPING PACKAGE (503419-0**8 SERIES)			
	10 OVER 30 UNDER	± ---	CHECKED BY HIJIMA	DATE 2011/11/15	<b>molex</b> DOCUMENT NO. SD-503419-002 SHEET NO. 1 OF 2			
	30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2011/11/16				
ANGULAR ±1 °		MATERIAL NO. 503419-***0		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3						



SECTION Y-Y

32±0.3	28.4	14.2	33.4	18.2	503419-0810	81				
24±0.3	—	11.5	25.4	16.2	503419-0710	71				
				15.4	503419-0670	67				
E キャリアテープ幅 EMBOSSED TAPE WIDTH					D	C	B	A	EMBOSSED TYPE PACKAGE	極数 CIRCUITS
					オーダー番号 ORDER NO.					

SEE SHEET 1 OF 2 EC NO: J2015-0631 DRWN: NKONDO 2014/11/11 CHKD: TAKAHASHI 2014/11/11 APPR: YNOGAWA 2014/11/11	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY	DATE	TITLE					
	10 OVER 30 UNDER	± ---	CHECKED BY	DATE	0.2 FPC CONN. E/O TAPING PACKAGE (503419-0**8 SERIES)					
	30 OVER	± ---	APPROVED BY	DATE						
ANGULAR	±1 °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		503419-***0		SD-503419-002		2 OF 2				
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						